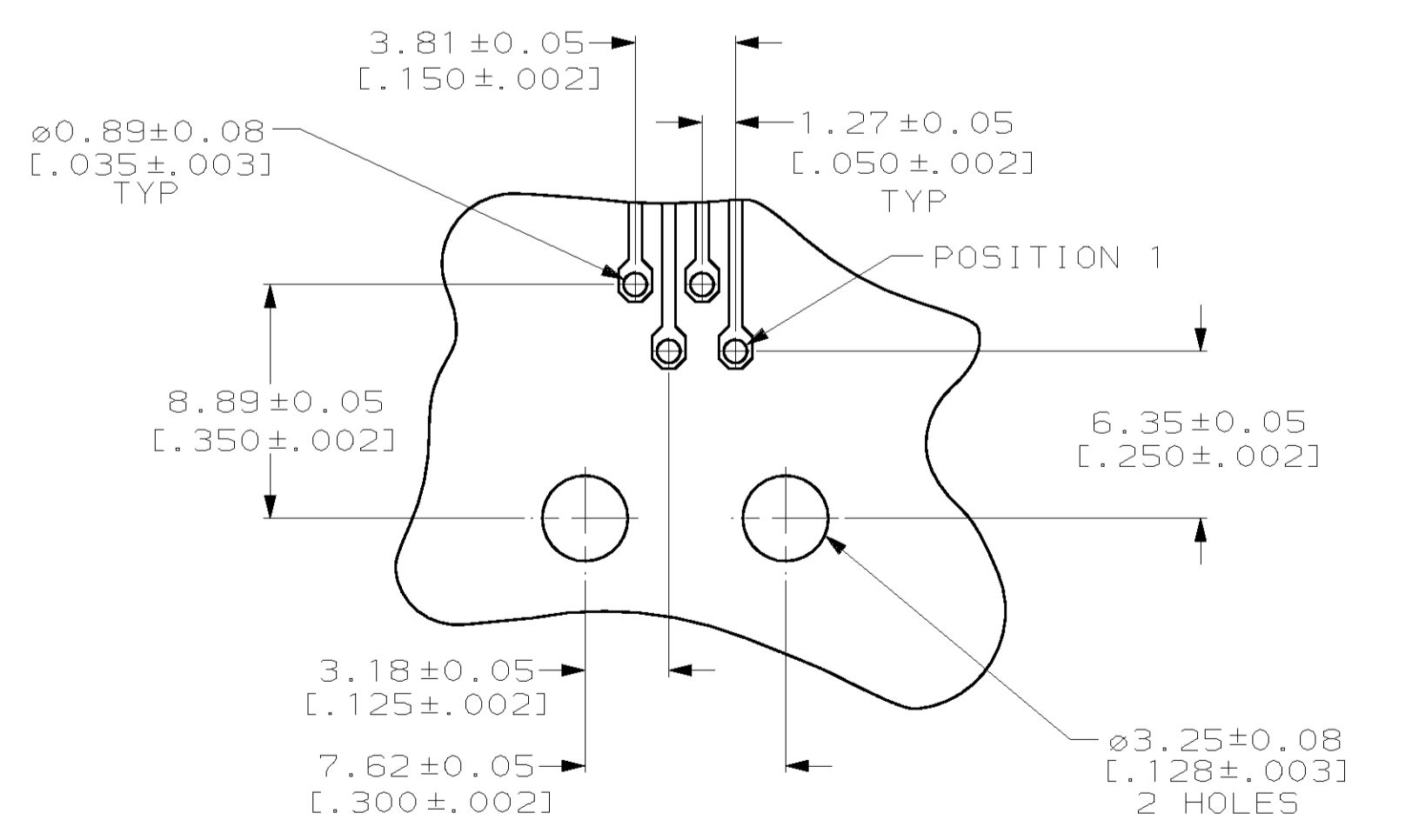
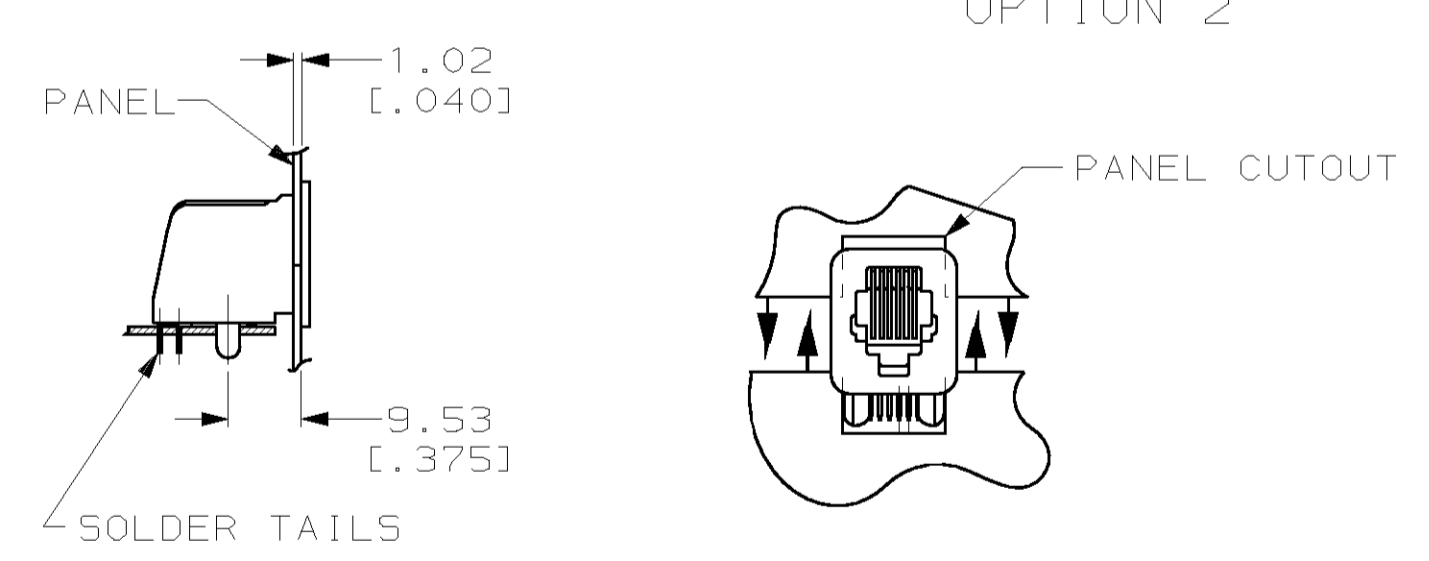
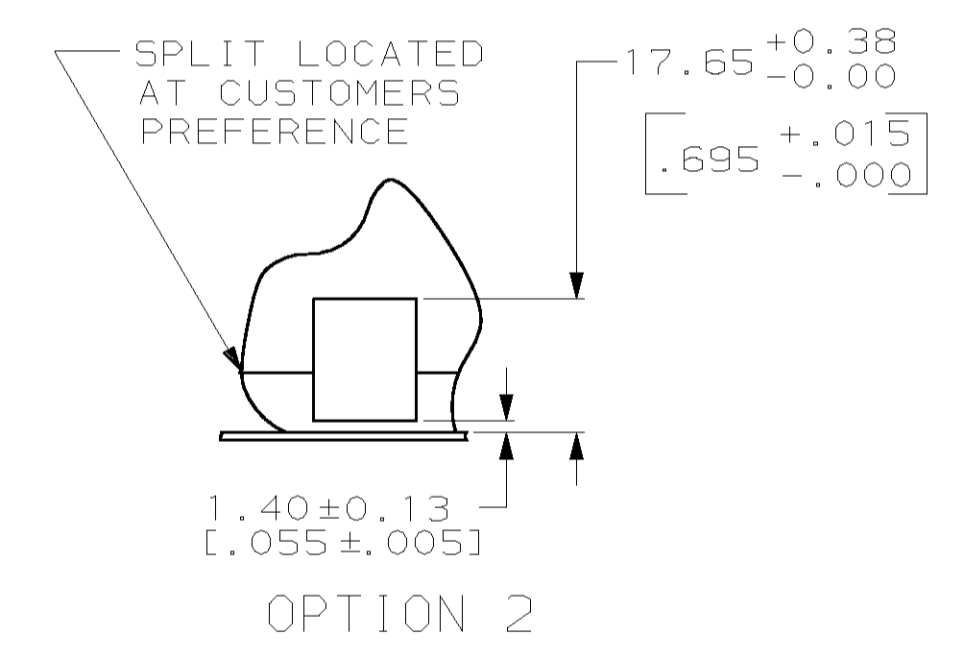
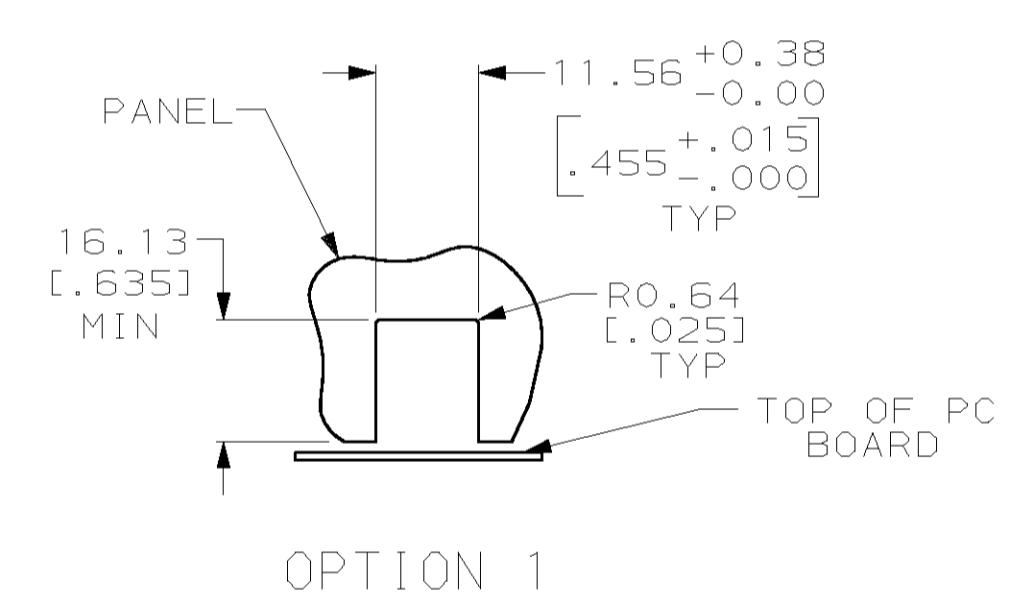
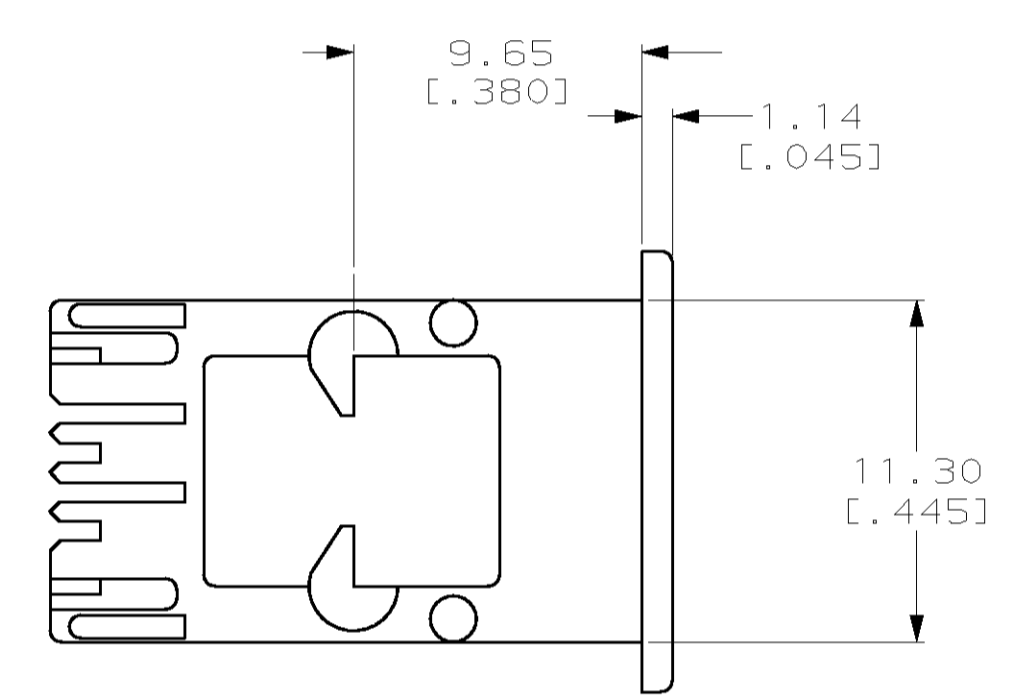
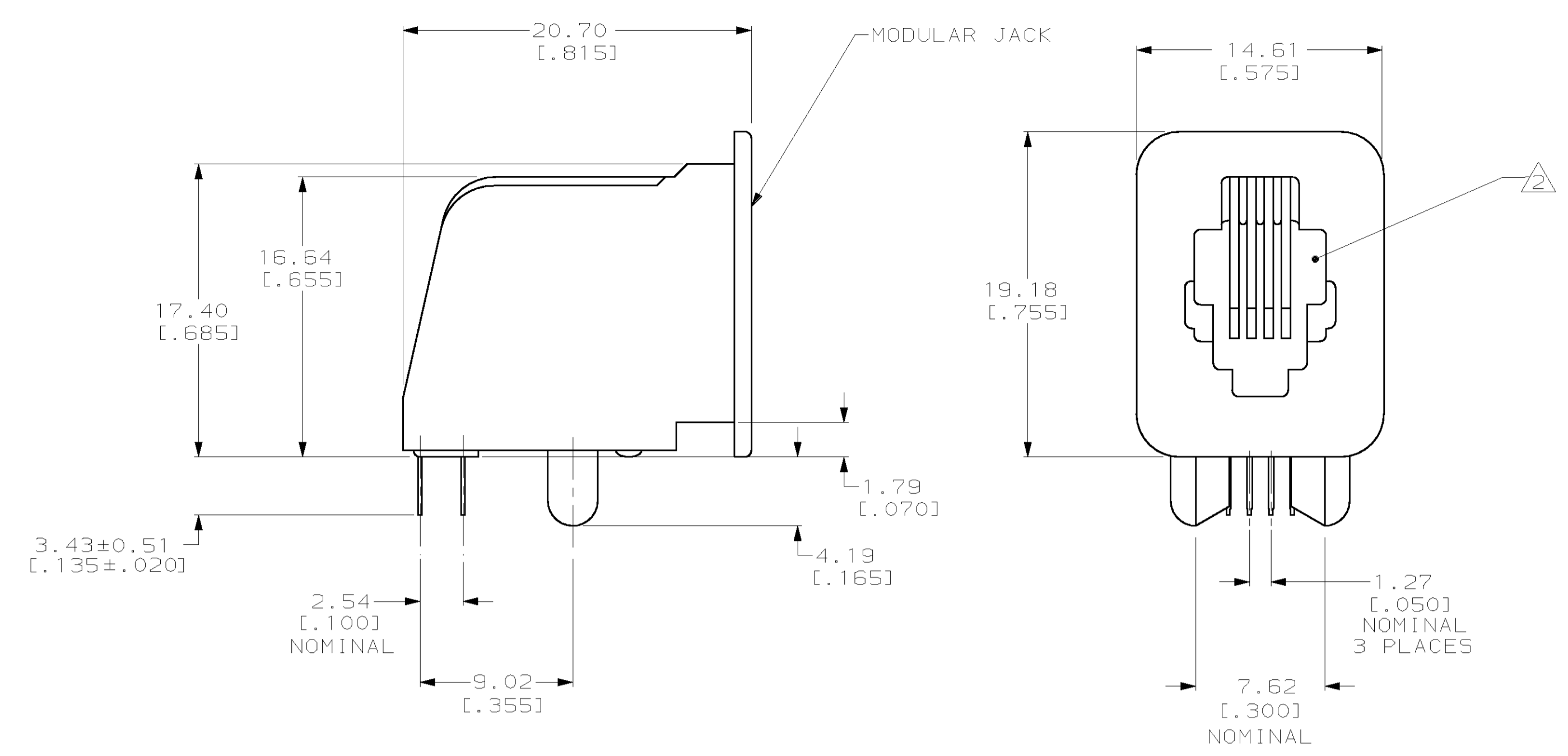


LOC	DIST	REVISIONS			
F	CHR	DESCRIPTION	DATE	OWN	APVD
E		REVISED, EC 0210-0051-94	10MAR94	KT	NJ



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (VIEW SHOWN IS CIRCUIT SIDE OF BOARD)

- 1 MATERIAL: HOUSING - PBT POLYESTER (BLACK).
 TERMINAL - 0.35 [.0138] THICK PHOS-BRONZE PLATED WITH 0.0013 [.00005] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 0.0020 [.00008] THICK TIN-LEAD IN SOLDER AREA OVER 0.0013 [.00005] THICK NICKEL UNDERPLATE.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 3. ALL DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.

520241-2
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWG: K. TILLMAN/UTA 10 MAR 94		AMP Incorporated	
DIMENSIONS: mm [INCHES]		CHK: N. JONES 01 APR 94		Harrisburg, PA 17105-3608	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: J. TONEY 01 APR 94		NAME: PRINTED CIRCUIT BOARD MODULAR JACK ASSEMBLY, SIDE ENTRY, 4 POSITION, FLANGED	
0 PLC ±.01		PRODUCT SPEC: 108-1163		SIZE: 114-2048	
1 PLC ±.02		APPLICATION SPEC: 114-2048		WEIGHT: -	
2 PLC ±.03		MATERIAL: -		CUSTOMER DRAWING	
3 PLC ±.04		FINISH: -		SCALE: 4:1	
4 PLC ±.05		RESTRICTED TO: -		SHEET 1 OF 1	
ANGLES ±.01		A1 00779 520241		REV E	